



PK902 (v1.0) June 5, 2017

100% Material Declaration Data Sheet for 7-Series Artix

FFG1156 RoHS 6/6

Average Weight : 9.7213 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die					0.237267	2.441%
	Silicon	7440-21-3	100.00	basis	0.237267	
Bump					0.009525	0.098%
	Tin	7440-31-5	98.20	basis	0.009354	
	Silver	7440-22-4	1.80	basis	0.000171	
Underfill					0.036000	0.370%
	Bisphenol F type liquid	9003-36-5	15.00	basis	0.005400	
	1,6-Bis(2,3-	27610-48-6	10.00	basis	0.003600	
	Bisphenol A type liquid	25068-38-6	5.00	basis	0.001800	
	Amine type hardener	trade secret	10.00	basis	0.003600	
	Silicon dioxide	60676-86-0	58.00	filler	0.020880	
	Carbon black	1333-86-4	1.00	color agent	0.000360	
	Additives	trade secret	1.00	additives	0.000360	
Heat sink					5.088500	52.344%
	Copper	7440-50-8	98.35	Main material	5.004540	
	Nickel	7440-02-0	1.65	Main material	0.083960	
Heat sink adhesive					0.106000	1.090%
	Aluminium Oxide Al2O3	N/A	80.00	Main material	0.084800	
	Dimethyl siloxane,	68083-19-2	20.00	Main material	0.021200	
Solder ball					0.965683	9.934%
	Tin	7440-31-5	96.50	Main material	0.931884	
	Silver	7440-22-4	3.00	Main material	0.028970	
	Copper	7440-50-8	0.50	Main material	0.004828	
Substrate					3.278325	33.723%
	Copper	7440-50-8	36.26		1.188721	
	Tin	7440-31-5	0.81		0.026554	
	Silver	7440-22-4	0.03		0.000983	
	Core	N/A	49.14		1.610969	
	ABF	N/A	11.27		0.369468	
	Solder Mask	N/A	2.49		0.081630	

Revision History

Date	Version	Description of Revisions
6/5/2017	1.0	Initial Xilinx Release

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